

TYPICAL DEVICE CHARACTERISTICS

MAXIMUM RATINGS @ 25°C Unless Otherwise Specified

PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power (tp = 8/20μs) - See Figure 1	P _{PP}	600	Watts
Peak Pulse Current (tp = 8/20μs)	I _{PP}	30	Amps
Repetitive Peak Forward Current @ tp = 5μs, F=50kHz, Pin 2 to 3	I _{FRM}	700	mA
Operating Temperature	T _L	-55 to 150	°C
Storage Temperature	T _{STG}	-55 to 150	°C

ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified

PART NUMBER (Note 1)	DEVICE MARKING	RATED STAND-OFF VOLTAGE V _{WM} VOLTS	MINIMUM BREAKDOWN VOLTAGE @ 1mA V _(BR) VOLTS	MINIMUM SNAP BACK VOLTAGE @ I _{SB} = 50mA V _{SB} VOLTS	MAXIMUM CLAMPING VOLTAGE (Fig. 2) @ I _P = 2A V _C VOLTS	MAXIMUM CLAMPING VOLTAGE (Fig. 2) @ I _P = 5A V _C VOLTS	MAXIMUM CLAMPING VOLTAGE (Fig. 2) @ I _P = 30A V _C VOLTS
SLVU2.8	SLA	2.8	3.0	2.8	3.9	7.0	21.0

NOTES

1. Device measured from pin 3 to 1.

ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified

MAXIMUM CLAMPING VOLTAGE Pin 2 to 1 (Fig. 2) @ I _P = 5A V _C VOLTS	TYPICAL CLAMPING VOLTAGE Pin 2 to 1 (Fig. 2) @ I _P = 30A V _C VOLTS	MAXIMUM LEAKAGE CURRENT Pin 3 to 1 or Pin 2 to 1 @V _{WM} I _D μA	TYPICAL CAPACITANCE Pin 3 to 1 & 2 (Tied Together) @0V, 1MHz C pF	TYPICAL CAPACITANCE Pin 2 to 1 3 N.C. @0V, 1MHz C pF	MAXIMUM PEAK REVERSE VOLTAGE Pin 3 to 2 (Note 1) @I _T = 10μA V _{RRM} VOLTS	MAXIMUM REVERSE LEAKAGE VOLTAGE Pin 3 to 2 (Note 1) @V _{WM} = 2.8V I _{DR} μA	MAXIMUM FORWARD VOLTAGE Pin 2 to 3 (Note 1) @I _F = 1A T _P = 120μs V _F VOLTS
8.5	21.0	1.0	20	2.5	40	0.1	2

NOTES

1. Electrical characteristics for steering diodes.

TYPICAL DEVICE CHARACTERISTICS

FIGURE 1
PEAK PULSE POWER VS PULSE TIME

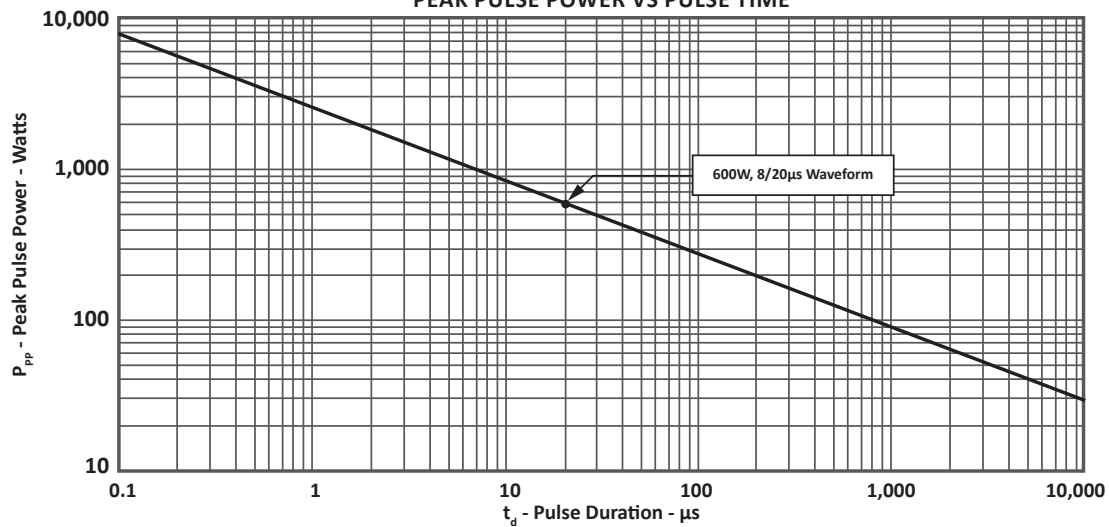
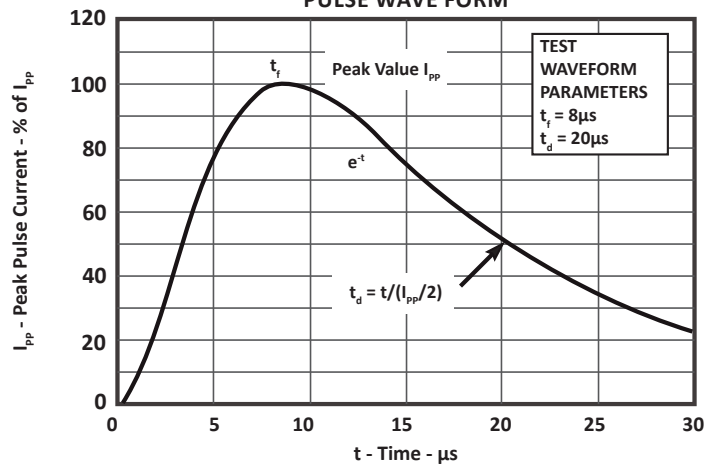
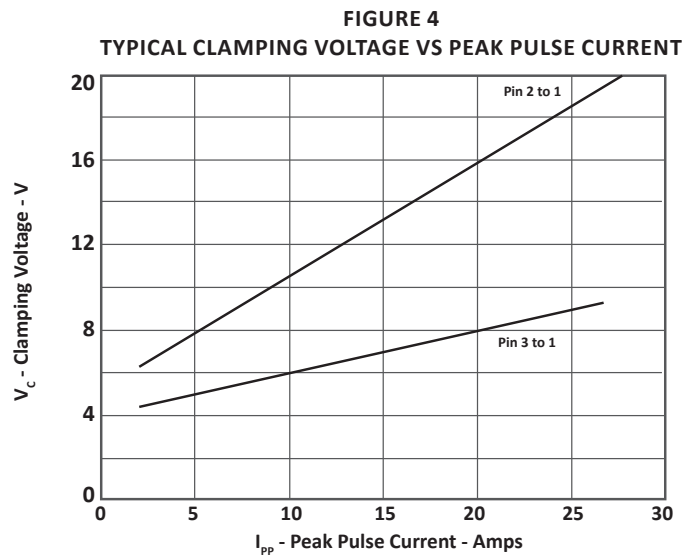
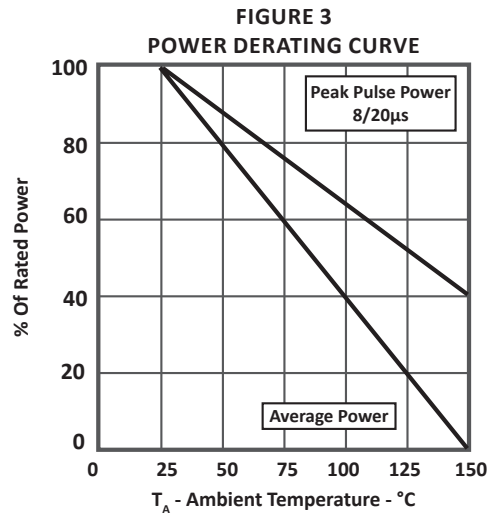


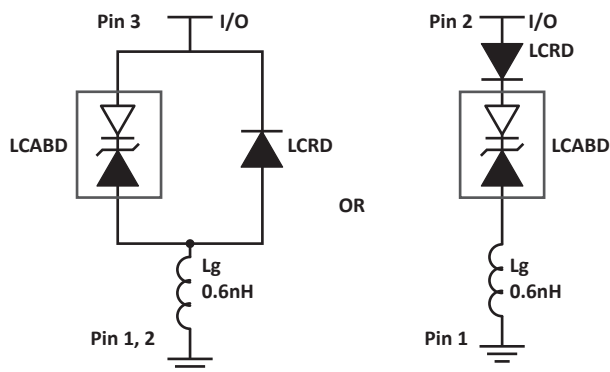
FIGURE 2
PULSE WAVE FORM



TYPICAL DEVICE CHARACTERISTICS



SPICE MODEL

FIGURE 1
SPICE MODEL


LCABD - Low Capacitance Avalanche Breakdown Diode (TVS)

LCRD: Low Capacitance Rectifier Diode

Lg - Lead Inductance

TABLE 1 - SPICE PARAMETERS			
PARAMETER	UNIT	ABD(TVS)	LCRD
BV	V	3.3	200
IBV	μA	1	0.01
C_{jo}	pF	20	5
I_s	A	1E-11	1E-13
Vj	V	-	0.6
M	-	0.33	0.33
N	-	1	1
R_s	Ohms	0.28	0.31
TT	s	1E-8	1E-9
EG	eV	1.11	1.11

APPLICATION INFORMATION

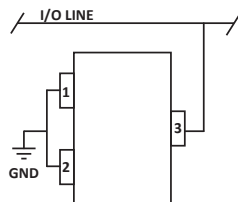


FIGURE 1 - UNIDIRECTIONAL COMMON MODE PROTECTION

Circuit connectivity is as follows:

- Line 1 connected to Pin 3.
- Pins 1 and 2 connected to ground.

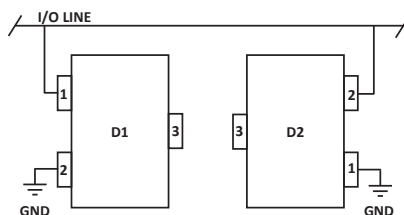


FIGURE 2 - BIDIRECTIONAL COMMON MODE PROTECTION

Two SLVU2.8 devices used in parallel. Circuit connectivity is as follows:

- Line 1 connected to Pin 1 of Device 1 and Pin 2 connected to Device 2.
- Pin 2 of Device 1 and Pin 1 of Device 2 connected to ground.
- Pin 3 of both Devices not connected.

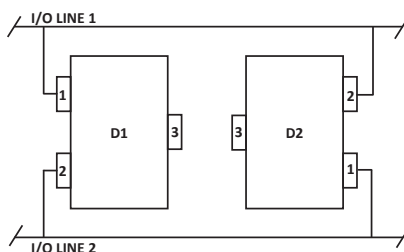


FIGURE 3 - BIDIRECTIONAL DIFFERENTIAL MODE PROTECTION

Two SLVU2.8 devices used in parallel. Circuit connectivity is as follows:

- Line 1 connected to Pin 1 of Device 1 and Pin 2 connected to Device 2.
- Line 2 connected to Pin 2 of Device 1 and Pin 1 of Device 2.
- Pin 3 not connected.

CIRCUIT BOARD RECOMMENDATIONS

Circuit board layout is critical for electromagnetic compatibility protection. The following guidelines are recommended:

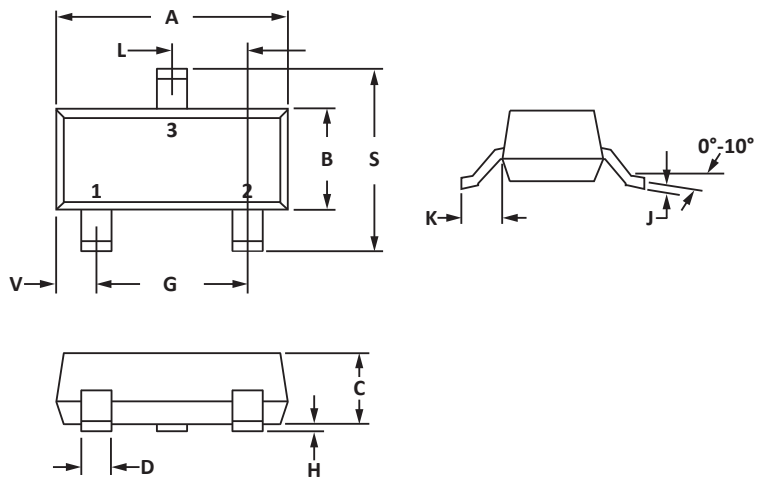
- The protection device should be placed near the input terminals or connectors, the device will divert the transient current immediately before it can be coupled into the nearby traces.
- The path length between the TVS device and the protected line should be minimized.
- All conductive loops including power and ground loops should be minimized.
- The transient current return path to ground should be kept as short as possible to reduce parasitic inductance.
- Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

SOT-23 PACKAGE INFORMATION
OUTLINE DIMENSIONS

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.80	3.04	0.110	0.120
B	1.20	1.40	0.047	0.055
C	0.89	1.11	0.035	0.044
D	0.37	0.50	0.015	0.020
G	1.78	2.04	0.070	0.081
H	0.013	0.100	0.001	0.004
J	0.085	0.177	0.003	0.007
K	0.45	0.60	0.018	0.024
L	0.89	1.02	0.035	0.040
S	2.10	2.50	0.083	0.098
V	0.45	0.60	0.018	0.024

NOTES

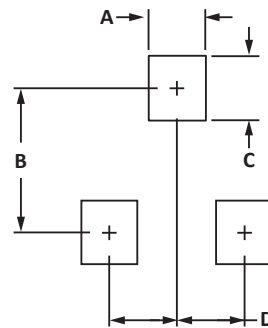
1. Controlling dimension: inches.
2. Dimensioning and tolerances per ANSI Y14.5M, 1985.
3. Pin 3 is the cathode (Unidirectional Only)
4. Dimensions are exclusive of mold flash and metal burrs.


PAD LAYOUT DIMENSIONS

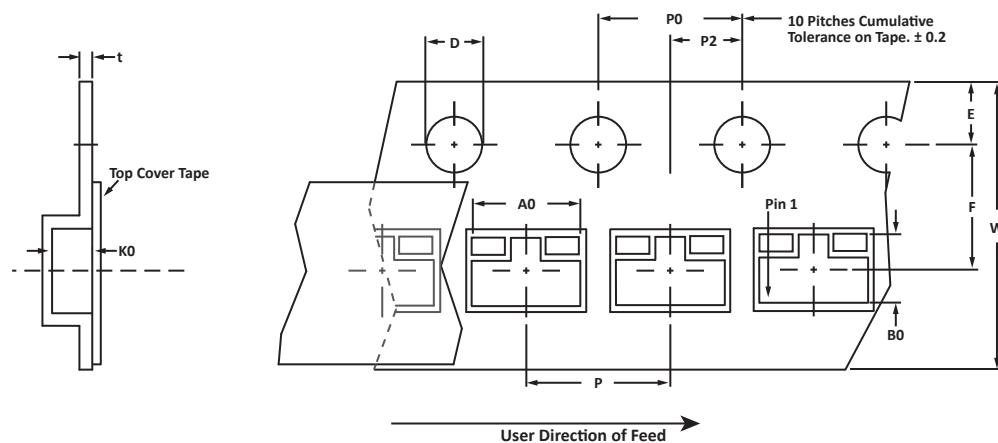
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.71	0.97	0.028	0.038
B	1.88	2.13	0.074	0.084
C	0.71	0.97	0.028	0.038
D	0.81	1.07	0.032	0.042

NOTES

1. Controlling dimension: inches.



TAPE AND REEL



SPECIFICATIONS

REEL DIA.	TAPE WIDTH	A0	B0	K0	D	E	F	W	P0	P2	P	tmax
178mm (7")	8mm	3.15 ± 0.10	2.77 ± 0.10	1.30 ± 0.10	1.55 ± 0.10	1.75 ± 0.10	3.50 ± 0.05	8.00 ± 0.30	4.00 ± 0.10	2.00 ± 0.05	4.00 ± 0.10	0.228

NOTES

1. Dimensions are in millimeters.
2. Surface mount product is taped and reeled in accordance with EIA-481.
3. Suffix - T7 = 7" Reel - 3,000 pieces per 8mm tape.
4. Suffix - T13 = 13" Reel - 10,000 pieces per 8mm tape.
5. Marking on Part - marking code (see page 2) and date code.

Package outline, pad layout and tape specifications per document number 06012.R2 8/10.

ORDERING INFORMATION

BASE PART NUMBER	LEADFREE SUFFIX	TAPE SUFFIX	QTY/REEL	REEL SIZE	TUBE QTY
SLVU2.8	-LF	-T7	3,000	7"	n/a
SLVU2.8	-LF	-T13	10,000	13"	n/a

This device is only available in a Lead-Free configuration.

COMPANY INFORMATION

COMPANY PROFILE

In business more than 25 years, ProTek Devices™ is a privately held semiconductor company. The company offers a product line of overvoltage protection and overcurrent protection components. These include transient voltage suppressor array (TVS arrays) avalanche breakdown diode, steering diode TVS array and electronics SMD chip fuses. These components deliver circuit protection in electronic systems from numerous overvoltage and overcurrent events. They include lightning; electrostatic discharge (ESD); nuclear electromagnetic pulses (NEMP); inductive switching; and electromagnetic interference (EMI) / radio frequency interference (RFI). ProTek Devices also offers LED wafer die for ESD protection and related high frequency products. ProTek Devices is ISO 9001:2015 certified.

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